


| | | |
|----------------------|------------------|---|
| MC240064GD6W-FPTLW | 128 x 64 | LCD Module |
| Specification | | |
| Version: 4 | Date: 13/04/2018 | |
| Revision | | |
| 1 | 15/10/2014 | First Issue. |
| 2 | 02/02/2015 | Modify Length of Cable. |
| 3 | 25/02/2016 | Modify Precautions in use of LCM and Static Electricity Test. |
| 4 | 07/02/2017 | Modify VIL. |

| Display Features | |  | |
|-----------------------|---------------------------|--|------------------|
| Resolution | 240 x 64 | | |
| Appearance | Black on White | | |
| Logic Voltage | 3.3V | | |
| Interface | Parallel | | |
| Font Set | N/A | | |
| Display Mode | Transflective | | |
| LC Type | FSTN | | |
| Module Size | 180.00 x 65.00 x 12.30 mm | | |
| Operating Temperature | -20°C ~ +70°C | | |
| Construction | COB | | |
| LED Backlight | White | Box Quantity | Weight / Display |
| | | ... | ... |

* - For full design functionality, please use this specification in conjunction with the RA6963 specification. (Provided Separately)

| Display Accessories | |
|------------------------------|---|
| Part Number | Description |
| MCCBLA120DILP -20DILS-150 | 20 Way Dual in line-to-Dual in line interconnect cable. |

| Optional Variants | |
|-------------------|---------|
| Appearances | Voltage |
| White on Blue | |



Contents

- 1.General Specification
- 2.Module Classification Information
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1. General Specification

The Features is described as follow:

- Module dimension: 180.0 x 65.0 x 12.3 (max.) mm
- View area: 133.0 x 39.0 mm
- Active area: 127.16 x 33.88 mm
- Number of dots: 240 x 64
- Dot size: 0.49 x 0.49 mm
- Dot pitch: 0.53 x 0.53 mm
- LCD type: FSTN Positive Transflective
- Duty: 1/64
- View direction: 6 o'clock
- Backlight Type: LED White
- IC: RA6963

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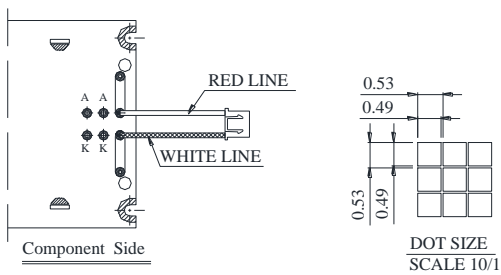
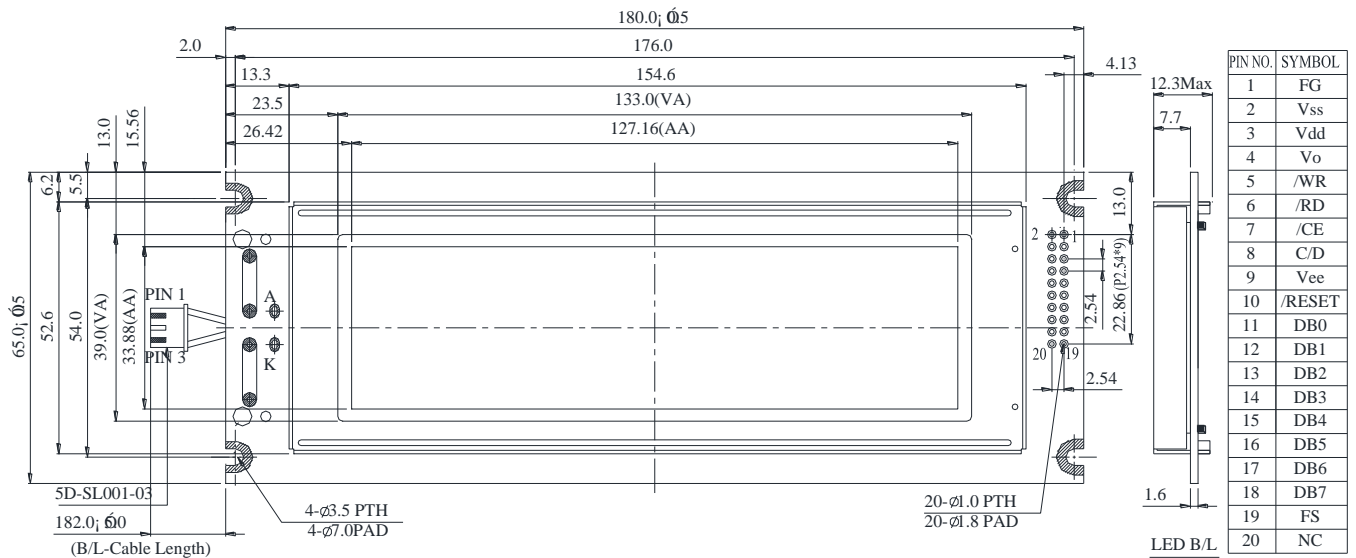
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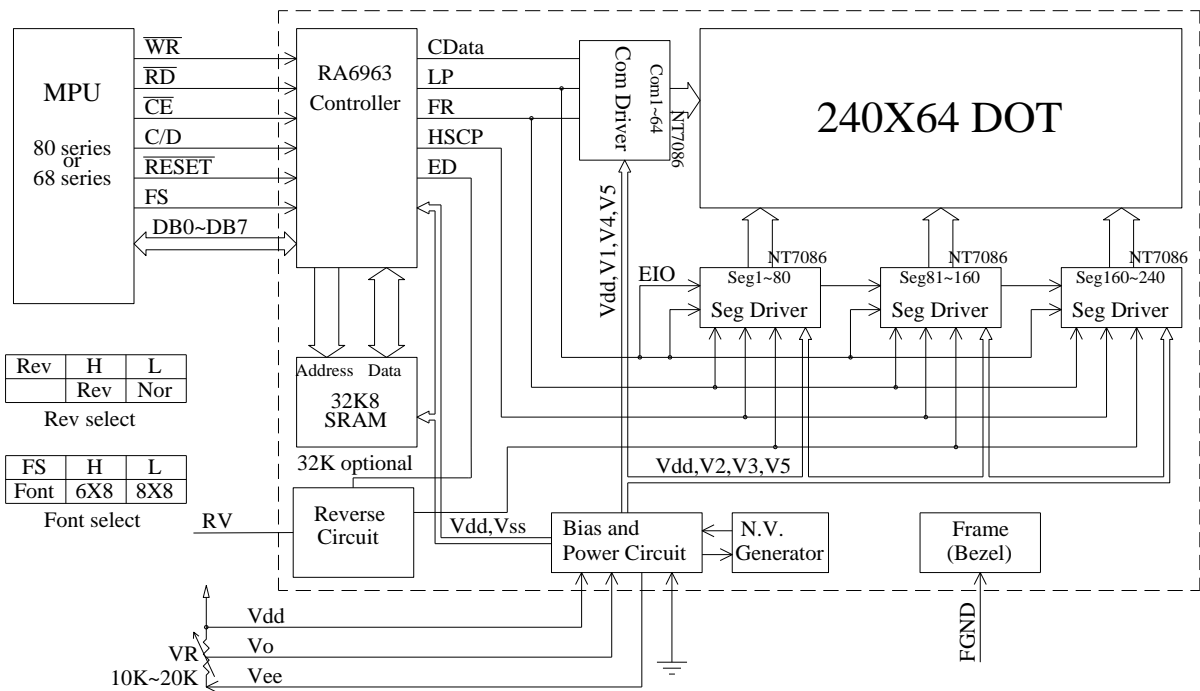
3.Interface Pin Function

| Pin No. | Symbol | Level | Description |
|---------|--------|-------|---|
| 1 | FG | — | Frame ground (Connected to bezel) |
| 2 | Vss | — | GND |
| 3 | Vdd | — | Power supply |
| 4 | Vo | — | Power supply for LCD driver |
| 5 | /WR | L | Data write. Write data into RA6963 when WR = L |
| 6 | /RD | L | Data read. Read data from RA6963 when RD = L |
| 7 | /CE | L | L : Chip enable |
| 8 | C/D | H / L | WR=L , C/D=H : Command Write C/D=L: Data write RD=L , C/D=H : Status Read C/D=L: Data read |
| 9 | Vee | — | Negative voltage output |
| 10 | /RESET | H / L | H : Normal ; L : Initialize RA6963 |
| 11 | DB0 | H / L | Data bus line |
| 12 | DB1 | H / L | Data bus line |
| 13 | DB2 | H / L | Data bus line |
| 14 | DB3 | H / L | Data bus line |
| 15 | DB4 | H / L | Data bus line |
| 16 | DB5 | H / L | Data bus line |
| 17 | DB6 | H / L | Data bus line |
| 18 | DB7 | H / L | Data bus line |
| 19 | FS | H / L | Pins for selection of font; H : 6 * 8 , L : 8 * 8 |
| 20 | NC | — | No connection |

4. Contour Drawing & Block Diagram



The non-specified tolerance of dimension is ± 0.3 mm.

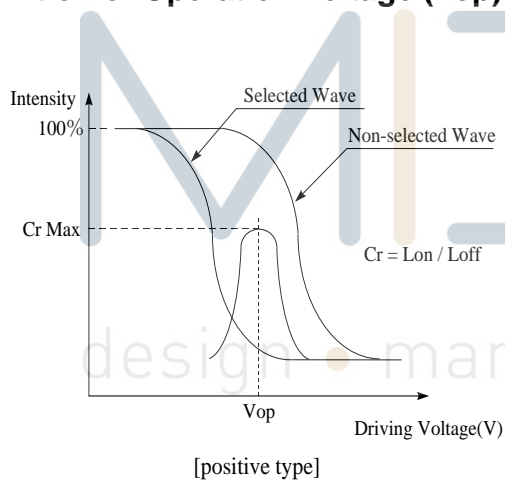


External contrast adjustment.

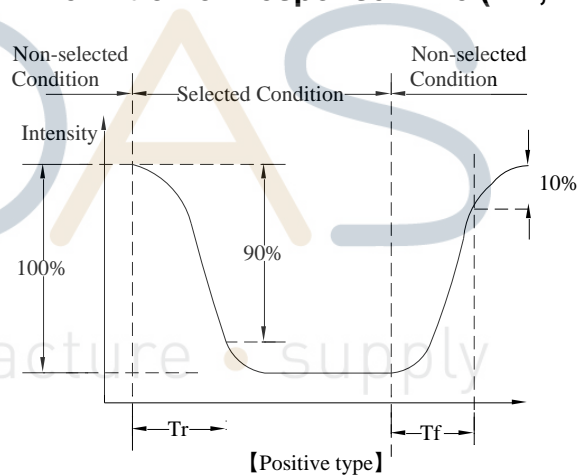
5.Optical Characteristics

| Item | Symbol | Condition | Min | Typ | Max | Unit |
|----------------|----------|-------------|-----|-----|-----|--------------------|
| View Angle | θ | $CR \geq 2$ | 0 | — | 30 | $\psi = 180^\circ$ |
| | θ | $CR \geq 2$ | 0 | — | 60 | $\psi = 0^\circ$ |
| | θ | $CR \geq 2$ | 0 | — | 45 | $\psi = 90^\circ$ |
| | θ | $CR \geq 2$ | 0 | — | 45 | $\psi = 270^\circ$ |
| Contrast Ratio | CR | — | — | 5 | — | — |
| Response Time | T rise | — | — | 200 | 300 | ms |
| | T fall | — | — | 250 | 350 | ms |

Definition of Operation Voltage (Vop)



Definition of Response Time (Tr , Tf)



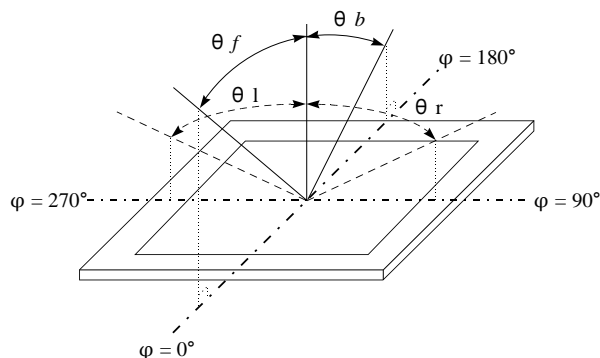
Conditions :

Operating Voltage : Vop

Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle($CR \geq 2$)



6. Absolute Maximum Ratings

| Item | Symbol | Min | Typ | Max | Unit |
|--------------------------|-----------------|------|-----|--------------|------|
| Operating Temperature | T_{OP} | -20 | — | +70 | °C |
| Storage Temperature | T_{ST} | -30 | — | +80 | °C |
| Input Voltage | V_{IN} | -0.3 | — | $V_{DD}+0.3$ | V |
| Supply Voltage For Logic | $V_{DD}-V_{SS}$ | -0.3 | — | +7.0 | V |

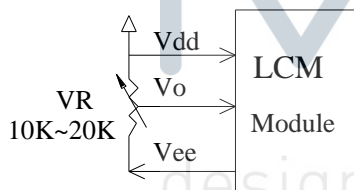
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7. Electrical Characteristics

| Item | Symbol | Condition | Min | Typ | Max | Unit |
|--------------------------|-----------------|---------------------------|--------------|------|---------------|------|
| Supply Voltage For Logic | $V_{DD}-V_{SS}$ | — | 3.0 | — | 5.5 | V |
| Supply Voltage For LCD | $V_{DD}-V_0$ | $T_a=-20^{\circ}\text{C}$ | — | — | 13.9 | V |
| *Note | | $T_a=25^{\circ}\text{C}$ | 12.1 | 12.5 | 12.9 | V |
| | | $T_a=70^{\circ}\text{C}$ | 10.1 | — | — | V |
| Input High Volt. | V_{IH} | — | $0.8V_{DD}$ | — | V_{DD} | V |
| Input Low Volt. | V_{IL} | — | 0 | — | $0.15 V_{DD}$ | V |
| Output High Volt. | V_{OH} | — | $V_{DD}-0.3$ | — | V_{DD} | V |
| Output Low Volt. | V_{OL} | — | 0 | — | 0.3 | V |
| Supply Current | I_{DD} | — | 12 | 16 | 20 | mA |

* Note: Please design the VOP adjustment circuit on customer's main board



8.Backlight Information

Specification

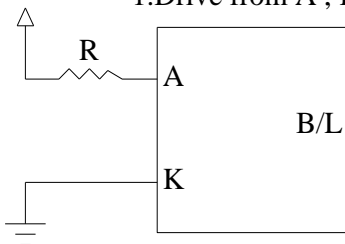
| PARAMETER | SYMBOL | MIN | TYP | MAX | UNIT | TEST CONDITION |
|---------------------------------------|------------------|-----|-----|-----|-------------------|--|
| Supply Current | I _{LED} | — | 80 | 100 | mA | V=3.5V |
| Supply Voltage | V | 3.4 | 3.5 | 3.6 | V | — |
| Reverse Voltage | V _R | — | — | 5 | V | — |
| Luminance (Without LCD) | I _V | 520 | 650 | — | CD/M ² | I _{LED} =80mA |
| LED Life Time (For Reference only) | — | — | 50K | — | Hr. | I _{LED} =80mA 25°C,50-60%RH, (Note 1) |
| Color | White | | | | | |

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.

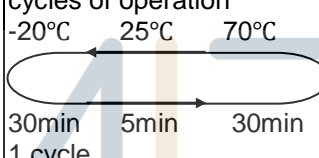
LED B\L Drive Method

1.Drive from A , K



9. Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

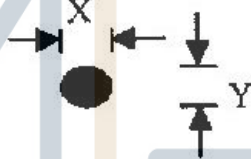
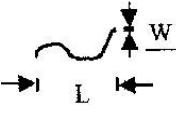
| Environmental Test | | | |
|------------------------------------|--|---|------|
| Test Item | Content of Test | Test Condition | Note |
| High Temperature storage | Endurance test applying the high storage temperature for a long time. | 80°C 200hrs | 2 |
| Low Temperature storage | Endurance test applying the low storage temperature for a long time. | -30°C 200hrs | 1,2 |
| High Temperature Operation | Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. | 70°C 200hrs | — |
| Low Temperature Operation | Endurance test applying the electric stress under low temperature for a long time. | -20°C 200hrs | 1 |
| High Temperature/ Humidity storage | The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature. | 60°C,90%RH 96hrs | 1,2 |
| Thermal shock resistance | The sample should be allowed stand the following 10 cycles of operation  | -20°C/70°C 10 cycles | — |
| Vibration test | Endurance test applying the vibration during transportation and using. | Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes | 3 |
| Static electricity test | Endurance test applying the electric stress to the terminal. | VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times | — |

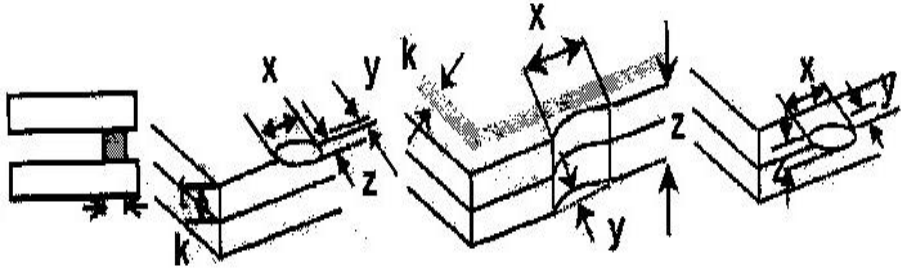
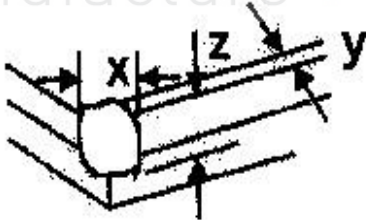
Note1: No dew condensation to be observed.

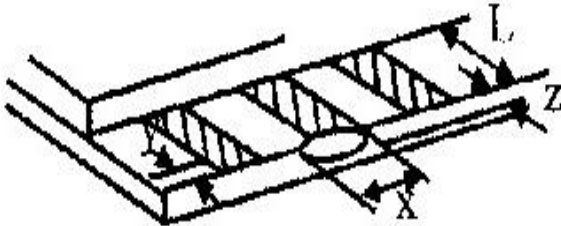
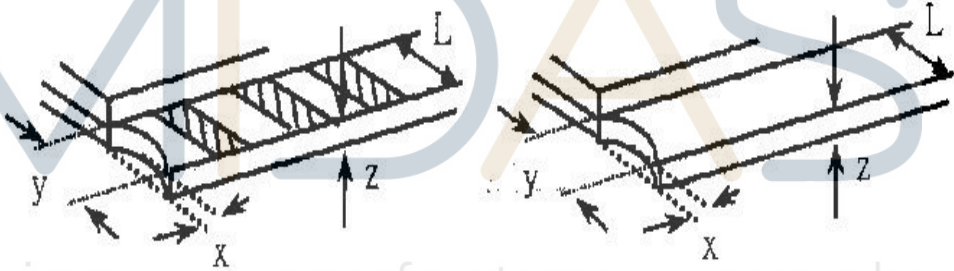
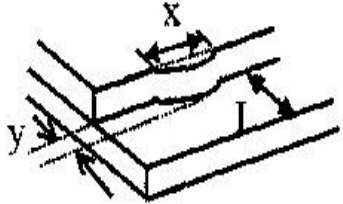
Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

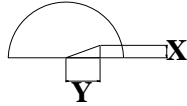
Note3: The packing have to including into the vibration testing.

10. Inspection specification

| NO | Item | Criterion | AQL | | | | | | | | | | | | |
|--|---|---|-----------------|-----------------|------------------|-----------------|-------------------------|----------------------|-------------------------|--------------|----------------------|-----|------------|---------------|-----|
| 01 | Electrical Testing | 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. | 0.65 | | | | | | | | | | | | |
| 02 | Black or white spots on LCD (display only) | 2.1 White and black spots on display $\leq 0.25\text{mm}$, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm | 2.5 | | | | | | | | | | | | |
| 03 | LCD black spots, white spots, contamination (non-display) | 3.1 Round type : As following drawing $\Phi = (x + y) / 2$  <table border="1" data-bbox="805 891 1332 1146"> <thead> <tr> <th>SIZE</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.10$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.10 < \Phi \leq 0.20$</td> <td>2</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.25$</td> <td>1</td> </tr> <tr> <td>$0.25 < \Phi$</td> <td>0</td> </tr> </tbody> </table> | SIZE | Acceptable Q TY | $\Phi \leq 0.10$ | Accept no dense | $0.10 < \Phi \leq 0.20$ | 2 | $0.20 < \Phi \leq 0.25$ | 1 | $0.25 < \Phi$ | 0 | 2.5 | | |
| | | SIZE | Acceptable Q TY | | | | | | | | | | | | |
| $\Phi \leq 0.10$ | Accept no dense | | | | | | | | | | | | | | |
| $0.10 < \Phi \leq 0.20$ | 2 | | | | | | | | | | | | | | |
| $0.20 < \Phi \leq 0.25$ | 1 | | | | | | | | | | | | | | |
| $0.25 < \Phi$ | 0 | | | | | | | | | | | | | | |
| 3.2 Line type : (As following drawing)  <table border="1" data-bbox="699 1281 1332 1534"> <thead> <tr> <th>Length</th> <th>Width</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> </tr> <tr> <td>$L \leq 3.0$</td> <td>$0.02 < W \leq 0.03$</td> <td rowspan="2">2</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.05$</td> </tr> <tr> <td>---</td> <td>$0.05 < W$</td> <td>As round type</td> </tr> </tbody> </table> | Length | Width | Acceptable Q TY | --- | $W \leq 0.02$ | Accept no dense | $L \leq 3.0$ | $0.02 < W \leq 0.03$ | 2 | $L \leq 2.5$ | $0.03 < W \leq 0.05$ | --- | $0.05 < W$ | As round type | 2.5 |
| Length | Width | Acceptable Q TY | | | | | | | | | | | | | |
| --- | $W \leq 0.02$ | Accept no dense | | | | | | | | | | | | | |
| $L \leq 3.0$ | $0.02 < W \leq 0.03$ | 2 | | | | | | | | | | | | | |
| $L \leq 2.5$ | $0.03 < W \leq 0.05$ | | | | | | | | | | | | | | |
| --- | $0.05 < W$ | As round type | | | | | | | | | | | | | |
| 04 | Polarizer bubbles | If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. <table border="1" data-bbox="826 1653 1332 1953"> <thead> <tr> <th>Size Φ</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.20$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.50$</td> <td>3</td> </tr> <tr> <td>$0.50 < \Phi \leq 1.00$</td> <td>2</td> </tr> <tr> <td>$1.00 < \Phi$</td> <td>0</td> </tr> <tr> <td>Total Q TY</td> <td>3</td> </tr> </tbody> </table> | Size Φ | Acceptable Q TY | $\Phi \leq 0.20$ | Accept no dense | $0.20 < \Phi \leq 0.50$ | 3 | $0.50 < \Phi \leq 1.00$ | 2 | $1.00 < \Phi$ | 0 | Total Q TY | 3 | 2.5 |
| Size Φ | Acceptable Q TY | | | | | | | | | | | | | | |
| $\Phi \leq 0.20$ | Accept no dense | | | | | | | | | | | | | | |
| $0.20 < \Phi \leq 0.50$ | 3 | | | | | | | | | | | | | | |
| $0.50 < \Phi \leq 1.00$ | 2 | | | | | | | | | | | | | | |
| $1.00 < \Phi$ | 0 | | | | | | | | | | | | | | |
| Total Q TY | 3 | | | | | | | | | | | | | | |

| NO | Item | Criterion | AQL | | | | | | | | | | | | | | | | | | |
|--------------------|-----------------------|--|-------------------|---------------|----------------|---------------|-----------------------|---------------|--------------------|-----------------|---------------|-------------------|---------------|----------------|---------------|-----------------------|---------------|--------------------|-----------------|---------------|-----|
| 05 | Scratches | Follow NO.3 LCD black spots, white spots, contamination | | | | | | | | | | | | | | | | | | | |
| 06 | Chipped glass | <p>Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length:</p> <p>6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="443 929 1353 1140"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙ If there are 2 or more chips, x is total length of each chip.</p> <p>6.1.2 Corner crack:</p>  <table border="1" data-bbox="443 1570 1353 1780"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙ If there are 2 or more chips, x is the total length of each chip.</p> | z: Chip thickness | y: Chip width | x: Chip length | $Z \leq 1/2t$ | Not over viewing area | $x \leq 1/8a$ | $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 1/8a$ | z: Chip thickness | y: Chip width | x: Chip length | $Z \leq 1/2t$ | Not over viewing area | $x \leq 1/8a$ | $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 1/8a$ | 2.5 |
| z: Chip thickness | y: Chip width | x: Chip length | | | | | | | | | | | | | | | | | | | |
| $Z \leq 1/2t$ | Not over viewing area | $x \leq 1/8a$ | | | | | | | | | | | | | | | | | | | |
| $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 1/8a$ | | | | | | | | | | | | | | | | | | | |
| z: Chip thickness | y: Chip width | x: Chip length | | | | | | | | | | | | | | | | | | | |
| $Z \leq 1/2t$ | Not over viewing area | $x \leq 1/8a$ | | | | | | | | | | | | | | | | | | | |
| $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 1/8a$ | | | | | | | | | | | | | | | | | | | |

| NO | Item | Criterion | AQL | | | | | | | | | | | | | | | | |
|-----------------------|----------------|---|---------------|----------------|-------------------|-----------------------|---------------|----------------|---------------|----------------|-------------------|------------|---------------|----------------|----------|-----------|---------------|------------|-----|
| 06 | Glass crack | <p>Symbols :</p> <p>x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length</p> <p>6.2 Protrusion over terminal :</p> <p>6.2.1 Chip on electrode pad :</p>  <table border="1" data-bbox="363 808 1286 909"> <thead> <tr> <th>y: Chip width</th> <th>x: Chip length</th> <th>z: Chip thickness</th> </tr> </thead> <tbody> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </tbody> </table> <p>6.2.2 Non-conductive portion:</p>  <table border="1" data-bbox="435 1294 1262 1406"> <thead> <tr> <th>y: Chip width</th> <th>x: Chip length</th> <th>z: Chip thickness</th> </tr> </thead> <tbody> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </tbody> </table> <p>⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</p> <p>⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.</p> <p>6.2.3 Substrate protuberance and internal crack.</p>  <table border="1" data-bbox="772 1711 1334 1812"> <thead> <tr> <th>y: width</th> <th>x: length</th> </tr> </thead> <tbody> <tr> <td>$y \leq 1/3L$</td> <td>$x \leq a$</td> </tr> </tbody> </table> | y: Chip width | x: Chip length | z: Chip thickness | $y \leq 0.5\text{mm}$ | $x \leq 1/8a$ | $0 < z \leq t$ | y: Chip width | x: Chip length | z: Chip thickness | $y \leq L$ | $x \leq 1/8a$ | $0 < z \leq t$ | y: width | x: length | $y \leq 1/3L$ | $x \leq a$ | 2.5 |
| y: Chip width | x: Chip length | z: Chip thickness | | | | | | | | | | | | | | | | | |
| $y \leq 0.5\text{mm}$ | $x \leq 1/8a$ | $0 < z \leq t$ | | | | | | | | | | | | | | | | | |
| y: Chip width | x: Chip length | z: Chip thickness | | | | | | | | | | | | | | | | | |
| $y \leq L$ | $x \leq 1/8a$ | $0 < z \leq t$ | | | | | | | | | | | | | | | | | |
| y: width | x: length | | | | | | | | | | | | | | | | | | |
| $y \leq 1/3L$ | $x \leq a$ | | | | | | | | | | | | | | | | | | |

| NO | Item | Criterion | AQL |
|----|--------------------|--|--|
| 07 | Cracked glass | The LCD with extensive crack is not acceptable. | 2.5 |
| 08 | Backlight elements | 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. | 0.65 2.5 0.65 |
| 09 | Bezel | 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications. | 2.5 0.65 |
| 10 | PCB - COB | 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  $X * Y \leq 2\text{mm}^2$ | 2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5 |
| 11 | Soldering | 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. | 2.5 2.5 2.5 0.65 |

| NO | Item | Criterion | AQL |
|----|--------------------|---|------|
| 12 | General appearance | 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. | 2.5 |
| | | 12.2 No cracks on interface pin (OLB) of TCP. | 0.65 |
| | | 12.3 No contamination, solder residue or solder balls on product. | 2.5 |
| | | 12.4 The IC on the TCP may not be damaged, circuits. | 2.5 |
| | | 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. | 2.5 |
| | | 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. | 2.5 |
| | | 12.7 Sealant on top of the ITO circuit has not hardened. | 0.65 |
| | | 12.8 Pin type must match type in specification sheet. | 0.65 |
| | | 12.9 LCD pin loose or missing pins. | 0.65 |
| | | 12.10 Product packaging must the same as specified on packaging specification sheet. | 0.65 |
| | | 12.11 Product dimension and structure must conform to product specification sheet. | 0.65 |
| | | 12.12 Visual defect outside of VA is not considered to be rejection. | |

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11. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Midas have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Midas have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

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12. Material List of Components for RoHs

1. Midas hereby declares that all of or part of products (with the mark “#” in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

| Material | (Cd) | (Pb) | (Hg) | (Cr6+) | PBBs | PBDEs |
|---------------|---------|----------|----------|----------|----------|----------|
| Limited Value | 100 ppm | 1000 ppm | 1000 ppm | 1000 ppm | 1000 ppm | 1000 ppm |

Above limited value is set up according to RoHS.

2. Process for RoHS requirement : (only for RoHS inspection)

- (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :
Reflow : 250°C, 30 seconds Max. ;
Connector soldering wave or hand soldering : 320°C, 10 seconds max.
- (3) Temp. curve of reflow, max. Temp. : 235±5°C ;
Recommended customer's soldering temp. of connector : 280°C, 3 seconds.



13.Recommendable Storage

1. Place the panel or module in the temperature $25^{\circ}\text{C}\pm 5^{\circ}\text{C}$ and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module.

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